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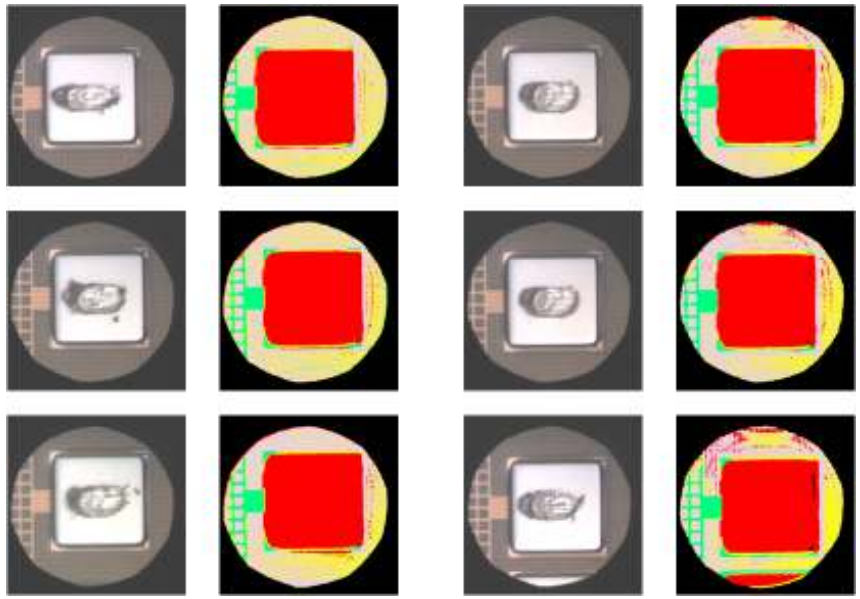
- These images are of contact pads on a Silicon semiconductor chip. The images on the left are the RGB image of the pad; the images on the right are the pseudo-colored spectrally analyzed data from the HSi300 (~480 to 620 nm). When the pad is intact, the center square of the classified image is entirely red.



Images Courtesy Applied Precision

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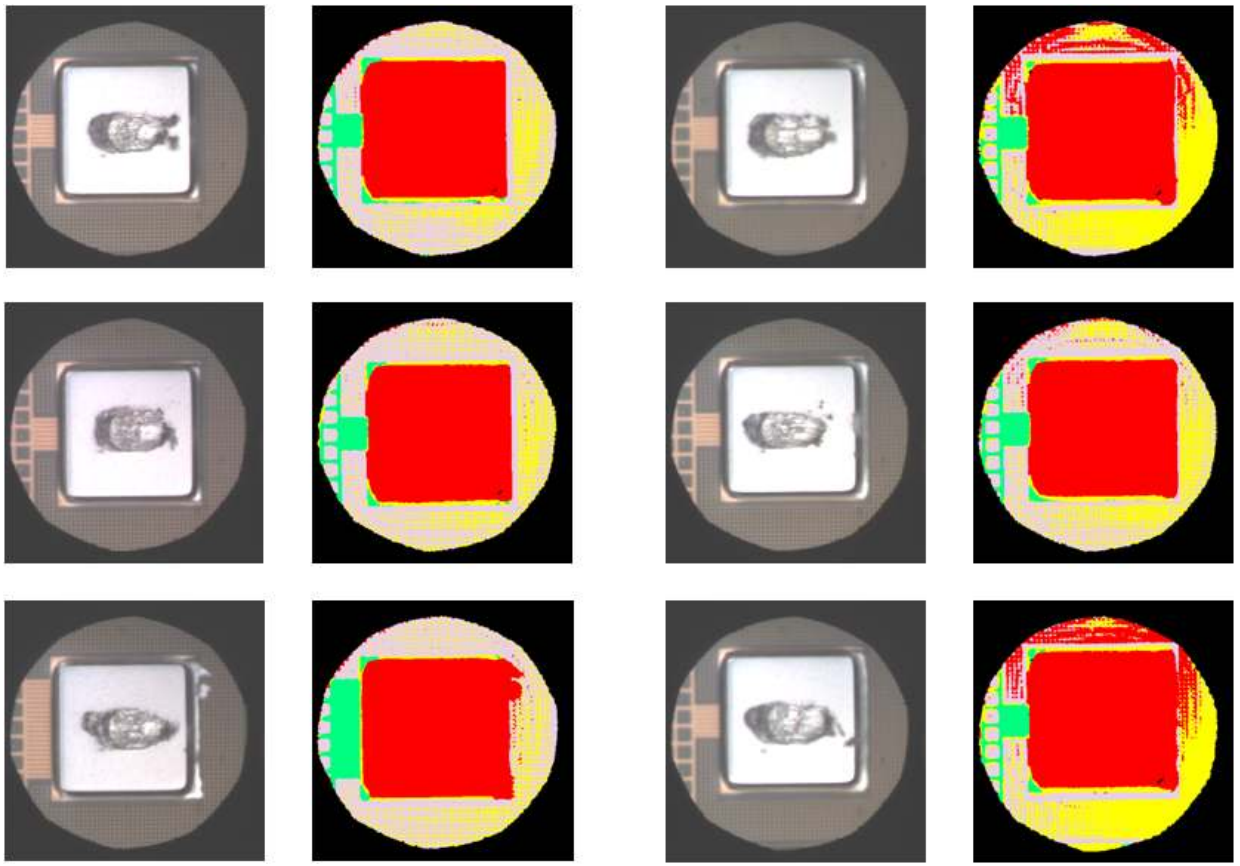

Images Courtesy Applied Precision

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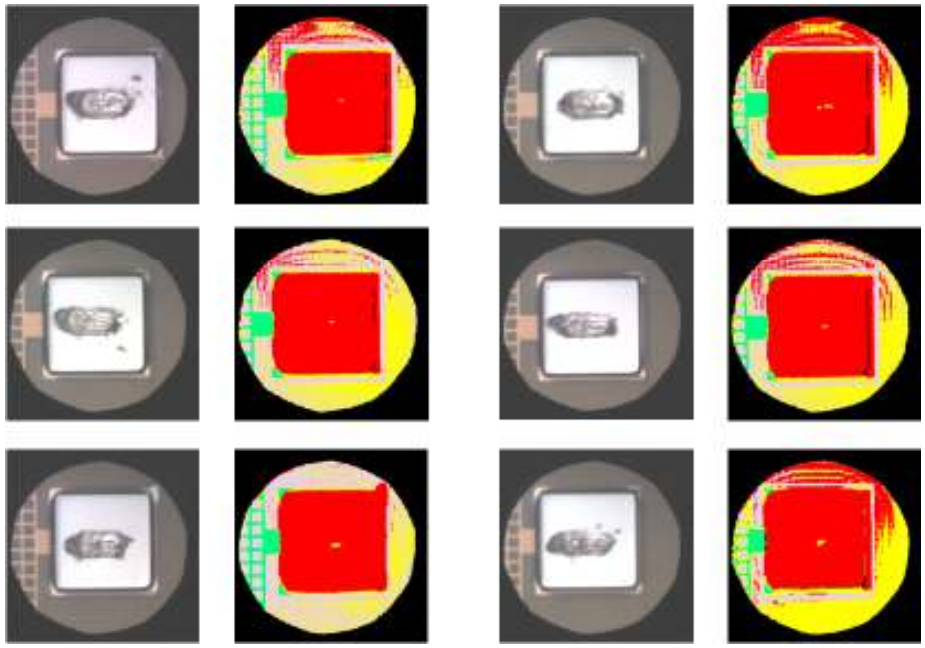
- When there is a defect in the upper layer of the pad, the aluminum underneath shows through, indicated by some yellow in the center of the red. This makes the chip unusable.
- Chip manufacturers at present can't detect this until they already manufactured the entire chip. The idea is to use spectral imaging to determine these defects early on.



Images Courtesy Applied Precision

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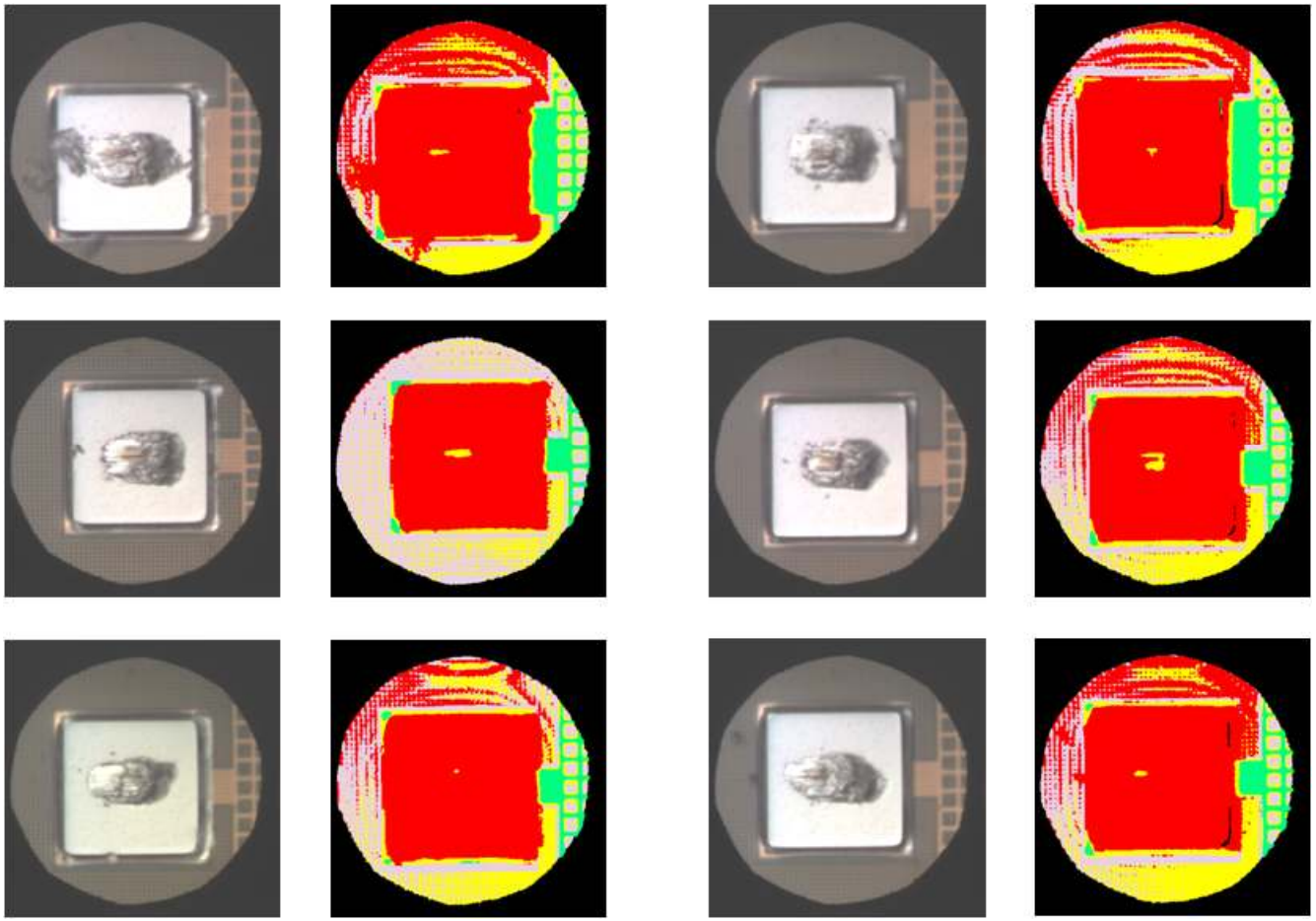

Images Courtesy Applied Precision

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